

RD Number: RD112

RD Title: TB67S149FG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	VM	1	Check terminal	-	-	Check pin		
2	VDD	1	Check terminal	-	-	Check pin		
3	GND	6	Check terminal	-	-	Check pin		
4	DMODE0	1	Check terminal	-	-	Check pin		
5	DMODE1	1	Check terminal	-	-	Check pin		
6	DMODE2	1	Check terminal	-	-	Check pin		
7	RESET	1	Check terminal	-	-	Check pin		
8	CLK	1	Check terminal	-	-	Check pin		
9	ENABLE	1	Check terminal	-	-	Check pin		
10	CW/CCW	1	Check terminal	-	-	Check pin		
11	COMA	1	Check terminal	-	-	Check pin		
12	OUTA+	1	Check terminal	-	-	Check pin		
13	OUTA-	1	Check terminal	-	-	Check pin		
14	OUTB-	1	Check terminal	-	-	Check pin		
15	OUTB+	1	Check terminal	-	-	Check pin		
16	COMB	1	Check terminal	-	-	Check pin		
17	VCOM	1	Check terminal	-	-	Check pin		
18	VCC	1	Check terminal	-	-	Check pin		
19	VREF	1	Check terminal	-	-	Check pin		
20	OSCM	1	Check terminal	-	-	Check pin		
21	ERR	1	Check terminal	-	-	Check pin		
22	MO	1	Check terminal	-	-	Check pin		
23	ZD	1	CMZ36	CMZ36	TOSHIBA	Zener diode	M-FLAT	
24	RVREF1	0	Not mount	-	-	Chip resistor		✓
25		0	Not mount	-	-	Leaded resistor		✓
26		2	Socket pin	-	-	Socket pin		

27	RVREF2	0	Not mount	–	–	Chip resistor		✓
28		0	Not mount	–	–	Leaded resistor		✓
29		2	Socket pin	–	–	Socket pin		
30	RERR	1	10kΩ 0.25W	–	–	Chip resistor	3.2mm×1.6mm	
31		0	10kΩ	–	–	Leaded resistor		✓
32	RMO	1	10kΩ 0.25W	–	–	Chip resistor	3.2mm×1.6mm	
33		0	10kΩ	–	–	Leaded resistor		✓
34	ROSCM	0	10kΩ 0.25W	–	–	Chip resistor	3.2mm×1.6mm	✓
35		1	10kΩ	–	–	Leaded resistor		
36		2	Socket pin	–	–	Socket pin		
37	CVM1	1	100μF 50V YK	–	–	Electrolytic capacitor		
38	CVM2	1	0.1μF 100V	–	–	Chip capacitor		
39		0	0.1μF	–	–	Ceramic capacitor		✓
40	CVDD	1	10μF 50V	–	–	Electrolytic capacitor		
41	CVCC	1	0.1μF 100V	–	–	Chip capacitor		
42	C1	0	0.1μF	–	–	Chip capacitor	3.2mm×1.6mm	✓
43	C2	0	0.1μF	–	–	Chip capacitor	3.2mm×1.6mm	✓
44	C3	0	0.1μF	–	–	Chip capacitor	3.2mm×1.6mm	✓
45	C4	0	0.1μF	–	–	Chip capacitor	3.2mm×1.6mm	✓
46	C5	0	0.1μF	–	–	Chip capacitor	3.2mm×1.6mm	✓
47	C6	0	0.1μF	–	–	Chip capacitor	3.2mm×1.6mm	✓
48	C7	0	0.1μF	–	–	Chip capacitor	3.2mm×1.6mm	✓
49	C9	0	0.1μF	–	–	Chip capacitor	3.2mm×1.6mm	✓
50	C13	0	0.1μF	–	–	Chip capacitor	3.2mm×1.6mm	✓
51	C15	0	0.1μF	–	–	Chip capacitor	3.2mm×1.6mm	✓
52	C17	0	0.1μF	–	–	Chip capacitor	3.2mm×1.6mm	✓
53	JP1	1	Pin header 2P	–	–	Jumper		
54		1	Jumper socket	–	–	Jumper Short		
55	SW1	1	Pin header 3P	–	–	Jumper		
56	(DMODE0)	1	Jumper socket	–	–	Jumper Short		
57	SW2	1	Pin header 3P	–	–	Jumper		
58	(DMODE1)	1	Jumper socket	–	–	Jumper Short		
59	SW3	1	Pin header 3P	–	–	Jumper		
60	(DMODE2)	1	Jumper socket	–	–	Jumper Short		

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